

# LArCADE | Liquid Argon Charge Amplification Devices

## Tiny Tips, Big Signals: Toward Low-Threshold CEvNS Imaging in Argon

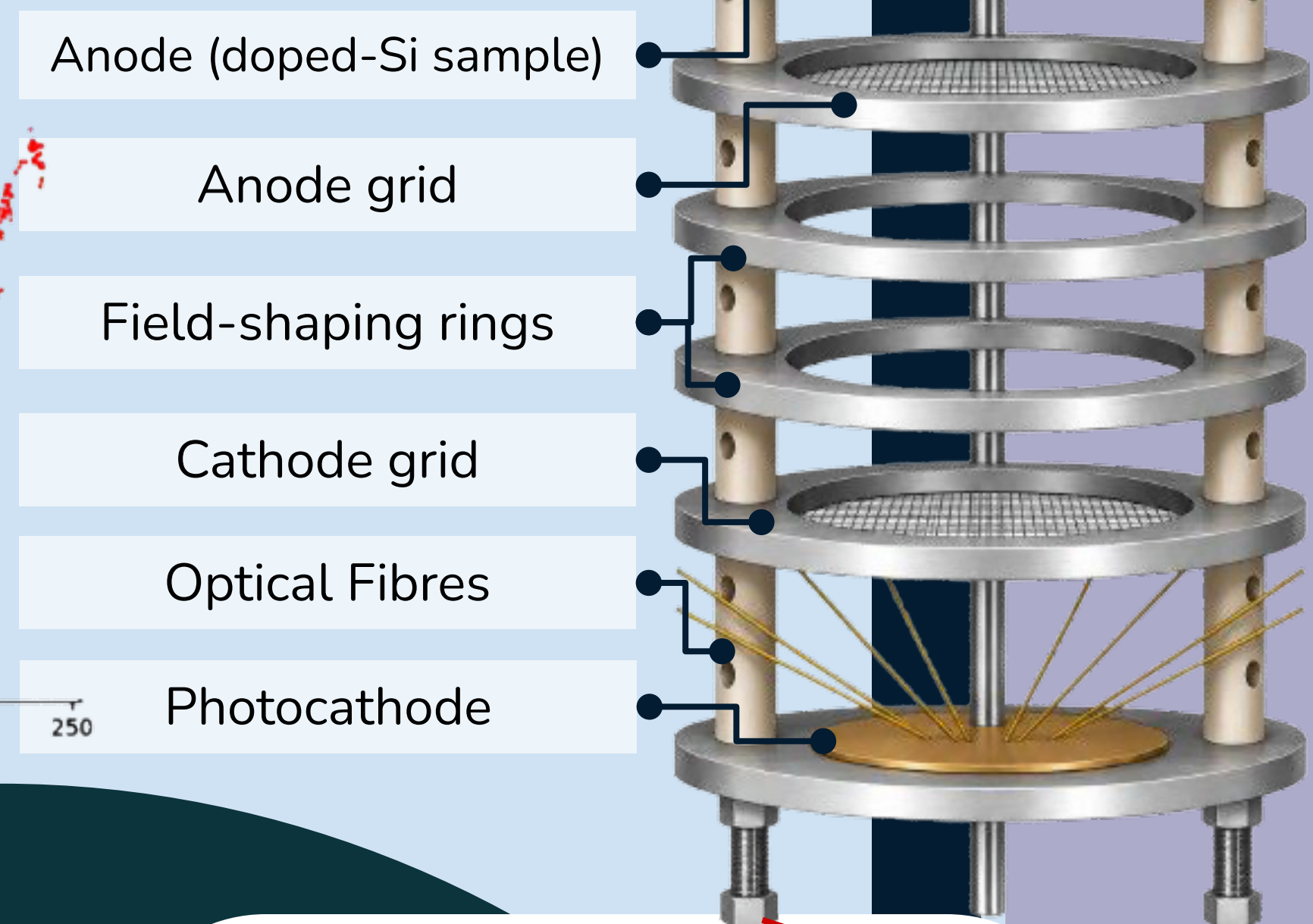
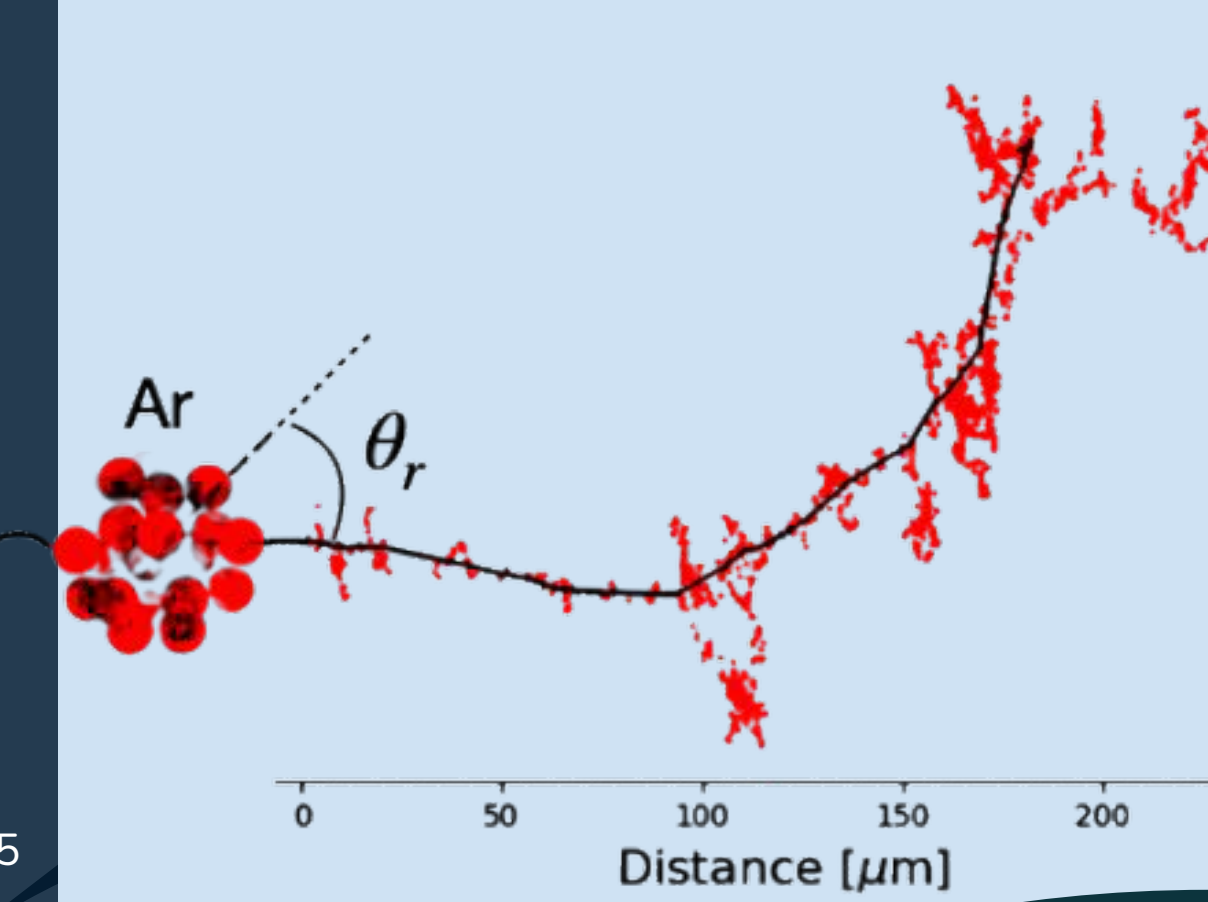
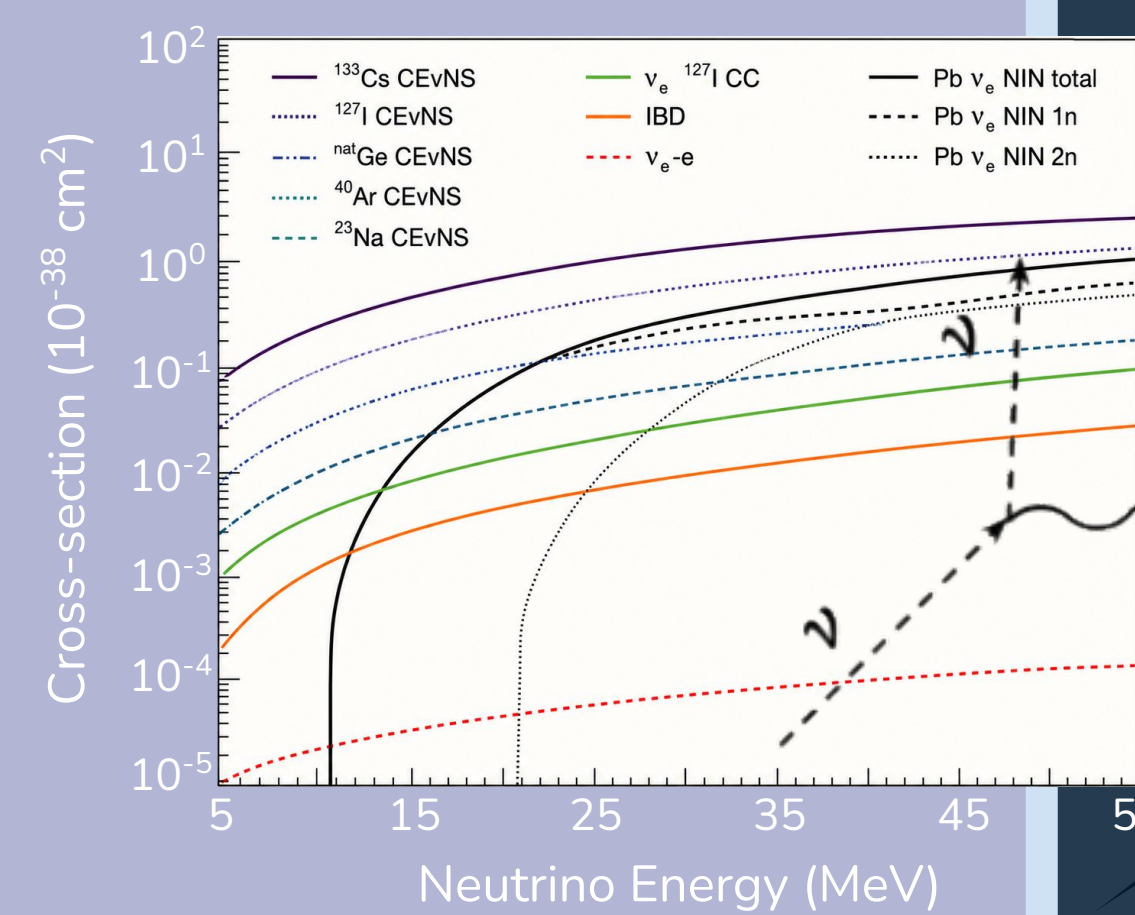
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### THE PHYSICS CASE<sup>1</sup>

Why CEvNS in LAr?

- CEvNS is a clean neutral-current probe of neutrino and BSM physics
- To fully exploit it we need the recoil energy and direction
- In argon, CEvNS recoils are short and weakly ionising, producing only  $O(10s-100) e^-$
- This pushes signals toward current LArTPC electronics-noise limits  $O(100s-1k)$
- LArCADE goal: stable, proportional charge amplification to enable low-threshold recoil imaging



### CURRENT STATUS

- Using conventional microfabrication workflow
- These structures were used in initial amplification studies
- Established the first hardware platform for testing charge amplification concepts in LAr:

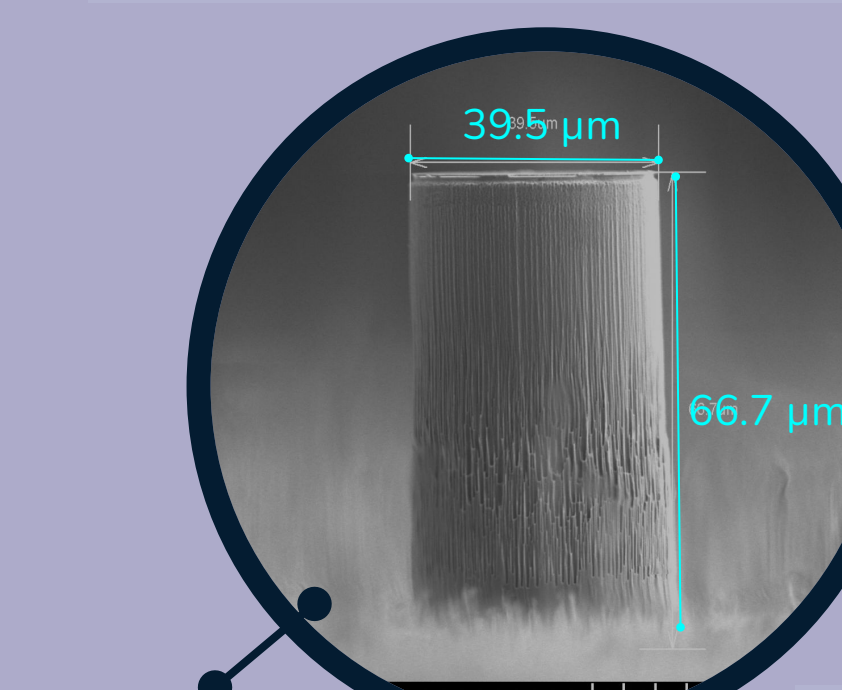
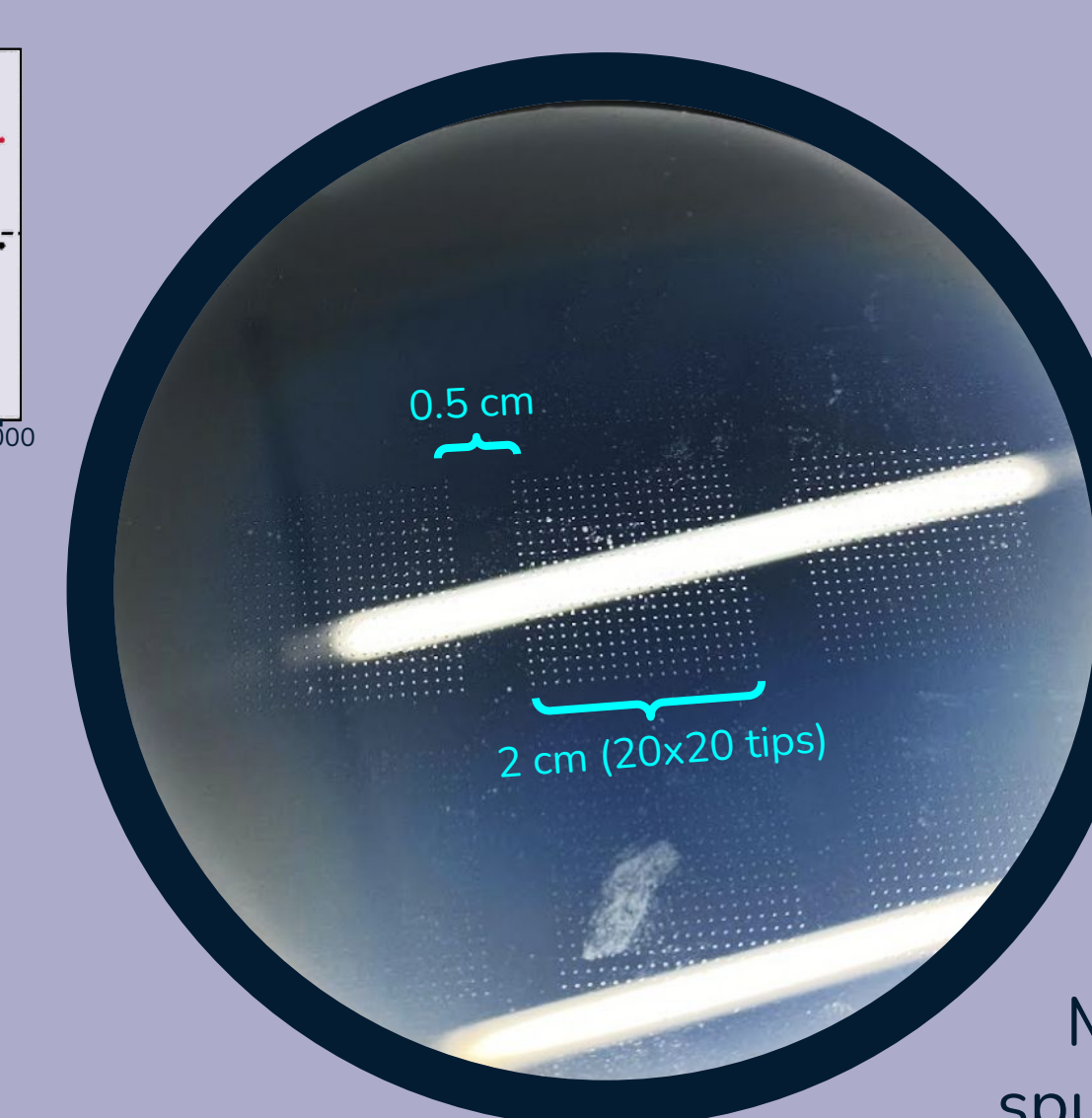
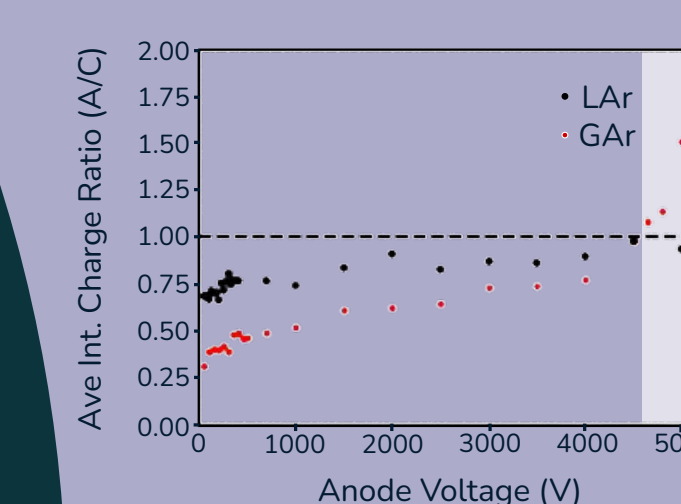


Photolithography



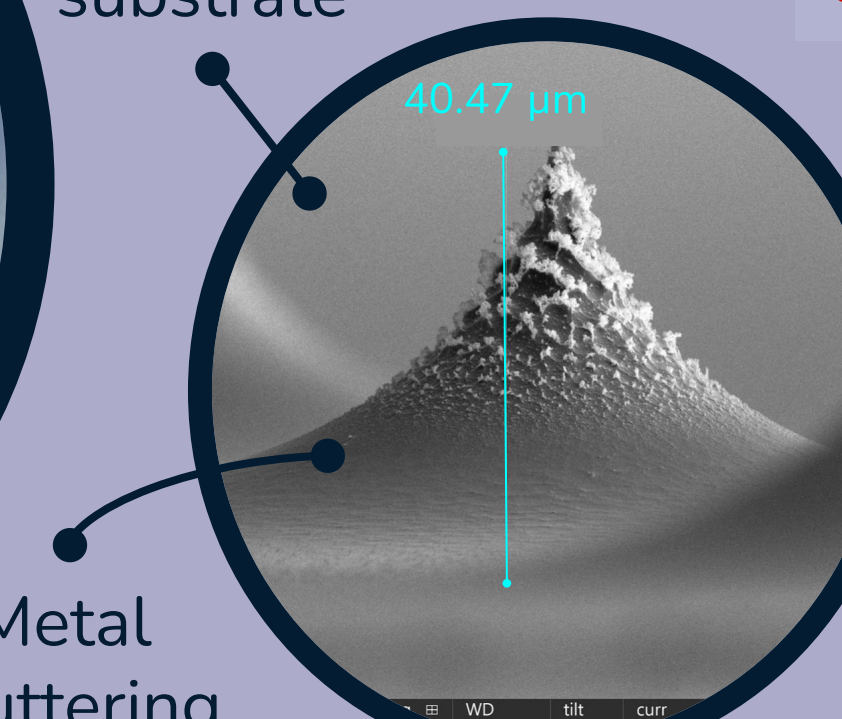
Mask Alignment & Deposition

Doped Si alone can produce clean, stable, reproducible photoelectron signals in vacuum!



doped-Si substrate

Etching & Sputtering



Metal sputtering

### AIM

Expand reach of large-scale single-phase LArTPCs to be sensitive to nuclear recoil ionisation signatures

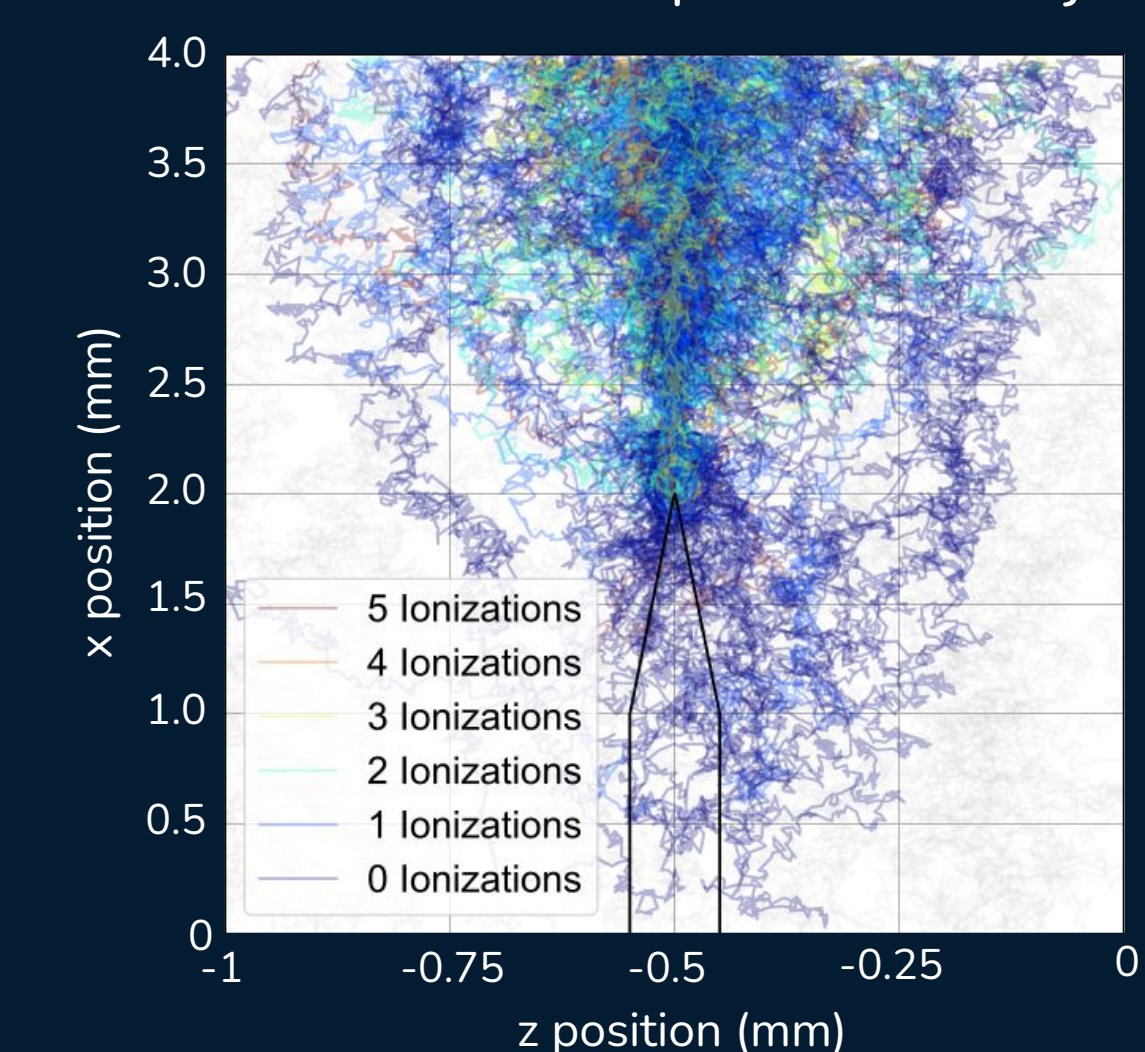
### TRANSLATE<sup>2</sup>

A custom first-principles micro-physics MC simulation of charge propagation, amplification & recombination in Argon.

- Electrons must reach  $O(10 \text{ eV})$  to ionise Ar and produce avalanche multiplication
- Dense LAr scattering competes with electron energy gain
- TRANSLATE models electron transport, scattering, excitation, and ionisation in non-uniform E-fields

- Benchmarked to data | GAR swarm parameters from LxCAT/Biagi databases, LAr mobility/diffusion from BNL/ICARUS/MicroBooNE.

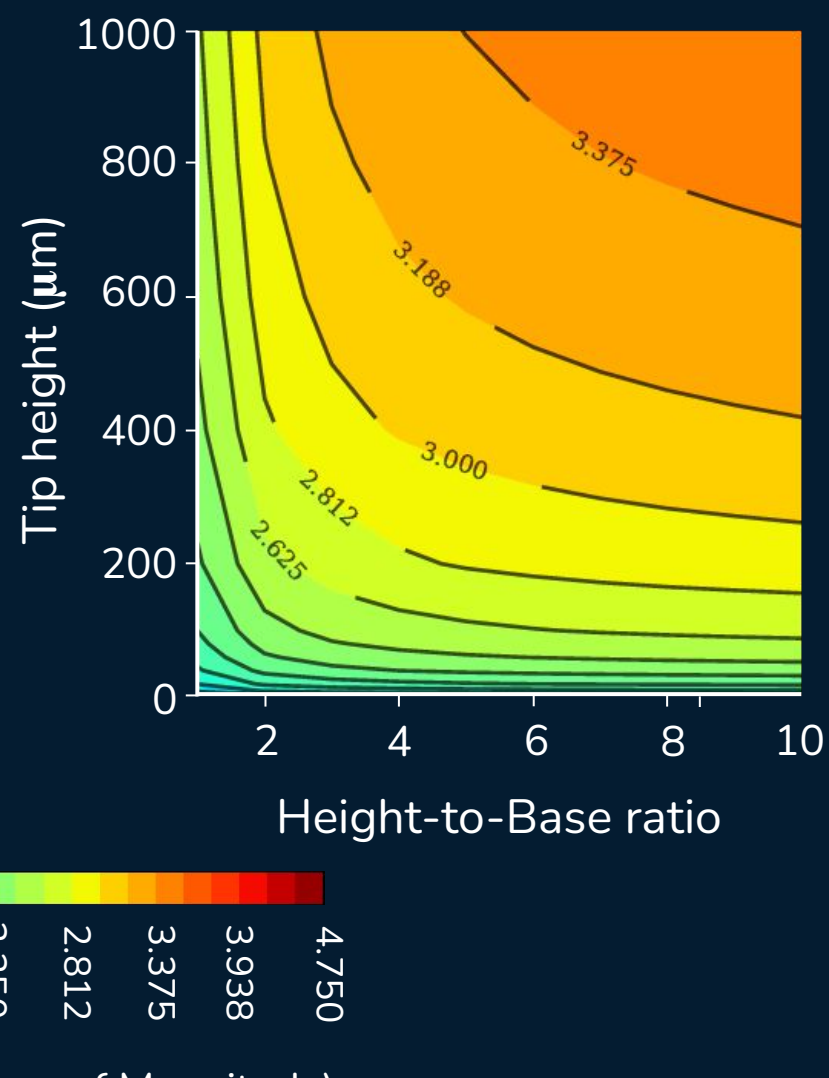
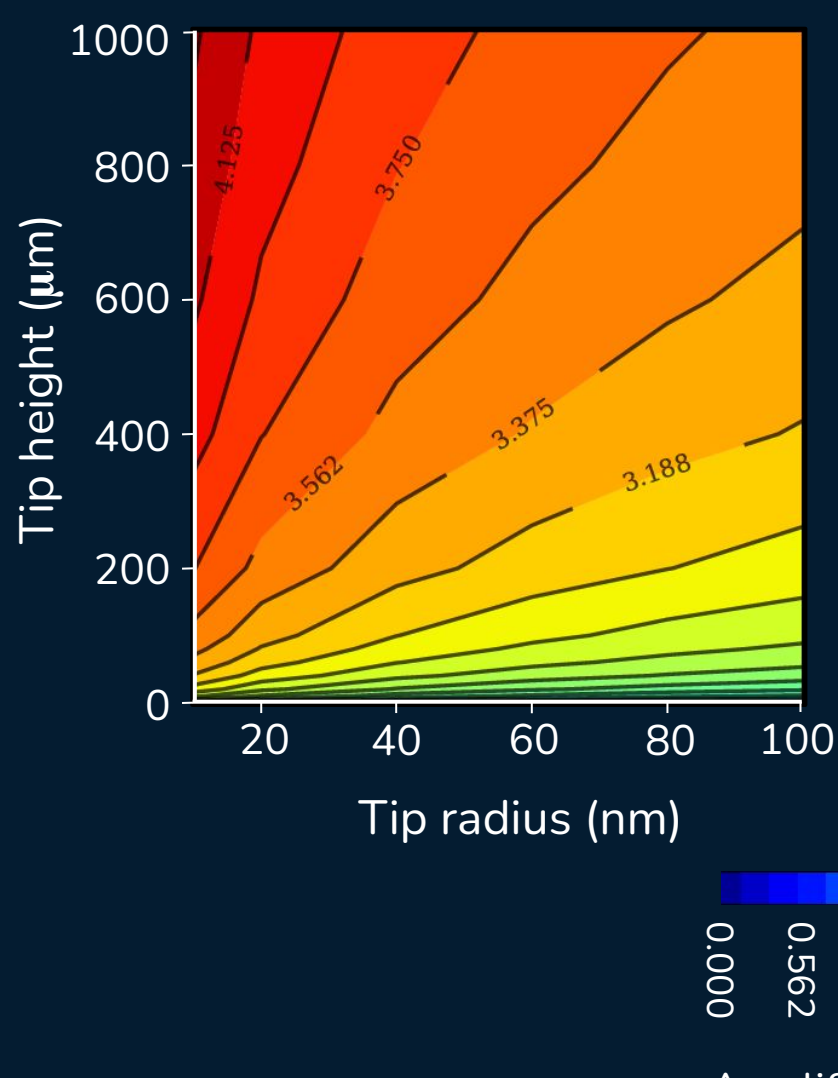
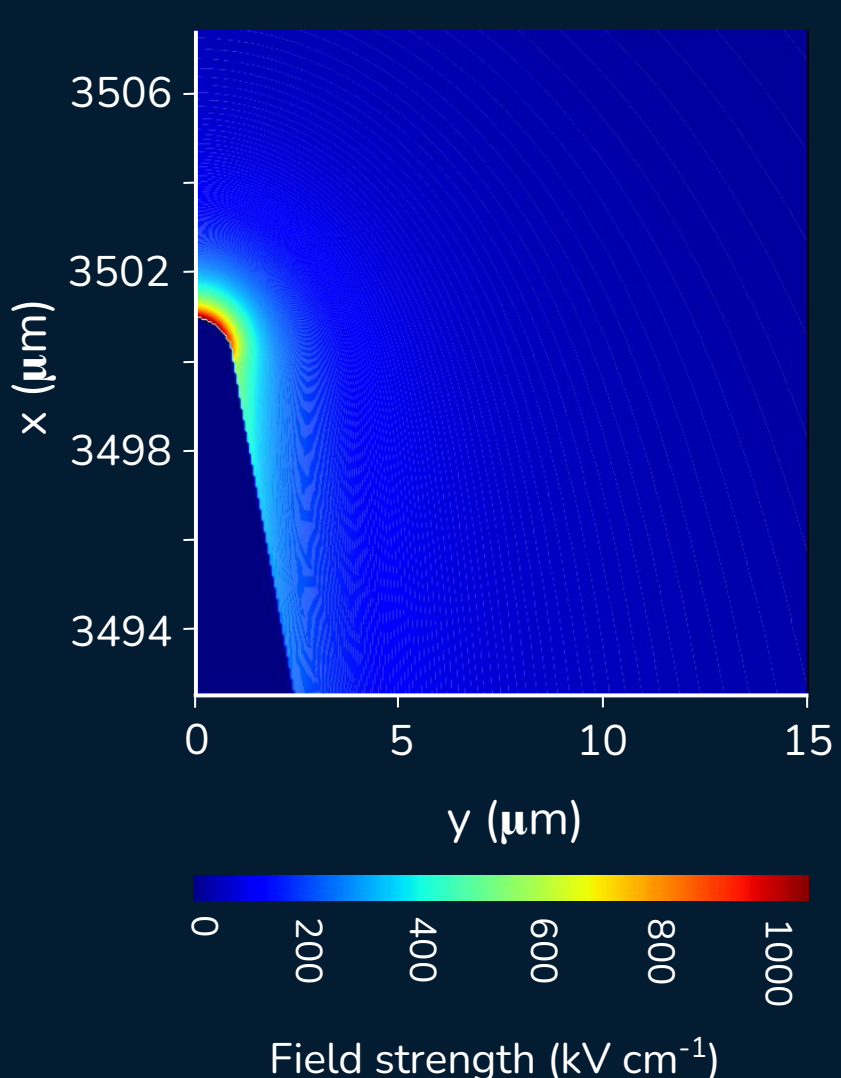
TRANSLATE: Near-Tip Electron Trajectories



- Simulation guides: tip radius, height, pitch, and operating field

Field near  $r = 1 \mu\text{m}$  Tip

Electric Field Amplification



### The Challenge

CEvNS nuclear recoils in LAr produce only  $O(10s-100)$  free electrons, near/below the noise scale of current LArTPC charge readout.

Sharp anode tips create intense local electric fields, aiming for stable, proportional charge amplification in Ar.

### Toward CEvNS Imaging

Local amplification can lift few-electron charge deposits above electronics noise while preserving spatial information.

### Big Signals, Localised Collection

LArCADE targets low-threshold,  $O(100 \mu\text{m})$  charge reconstruction for spatially resolved nuclear-recoil measurements.

### The Solution

#### Achievements

- Established LArCADE test bed for anode/tip R&D
- Benchmarked TRANSLATE electron-transport and amplification simulations
- Demonstrated stable GAR amplification with metal-sputtered Si tips
- Showed doped Si can produce stable signals without sputtering - characterisation of resistive anodes started as a parallel dedicated effort (MOSAIC)

#### Next Steps

- Fabricate KOH-defined Si nanotip arrays at UCSB
- Validate simulated gain predictions in GAR and LAR

#### References

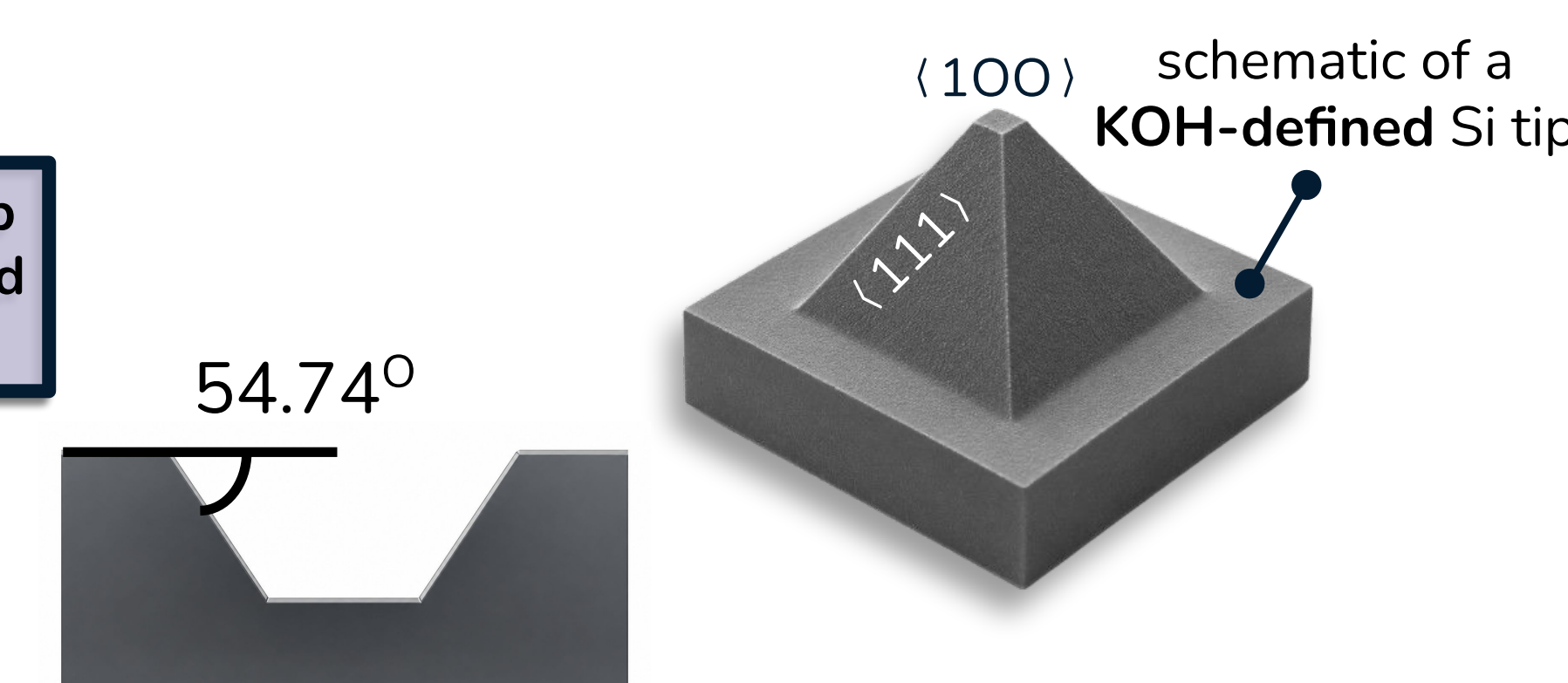
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- Yun et al., *J. Vac. Sci. Technol. B* 16, 2844 (1998).

### TAKEAWAYS

#### NEW!

Doped-Si truncated-pyramidal tip structures with tunable height and pitch using KOH wet-etching<sup>3</sup>

- $h = 100 \mu\text{m}$ ,  $20 \times 20$ ,  $1 \text{ mm}$  tip-tip
- $h = 100 \mu\text{m}$ ,  $100 \times 100$ ,  $200 \mu\text{m}$  tip-tip
- $h = 400 \mu\text{m}$ ,  $25 \times 25$ ,  $800 \mu\text{m}$  tip-tip



- Closed simulation-to-hardware loop: TRANSLATE outputs set mask geometry
- Doped-Si simplifies fabrication by eliminating sputtering while providing tunable conductivity
- KOH etching<sup>3</sup> of (100) Si forms sloped {111} facets set by crystal geometry
- Square cap masks protect the apex, leaving doped-Si tip structures after etching ( $10 \mu\text{m}$  square tip)
- 100–400  $\mu\text{m}$  tip heights and variable pitch/spacing tune field amplification
- CAD-generated  $3 \times 3$  layouts enable wafer-scale tip-array fabrication



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